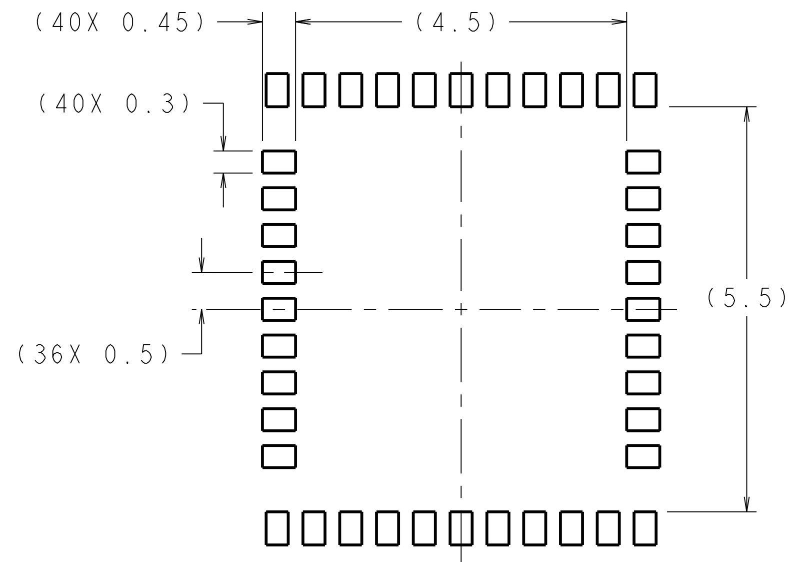
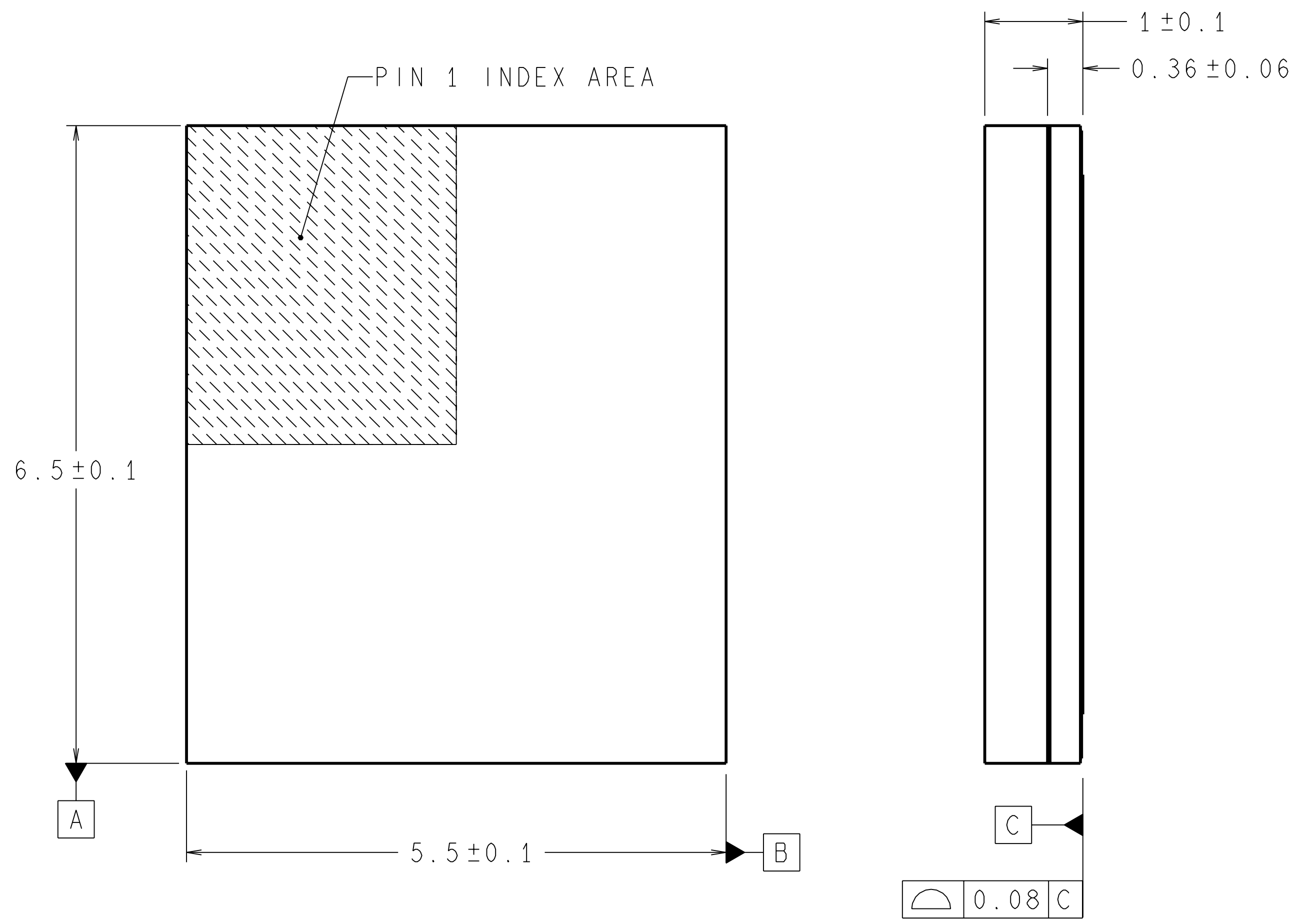
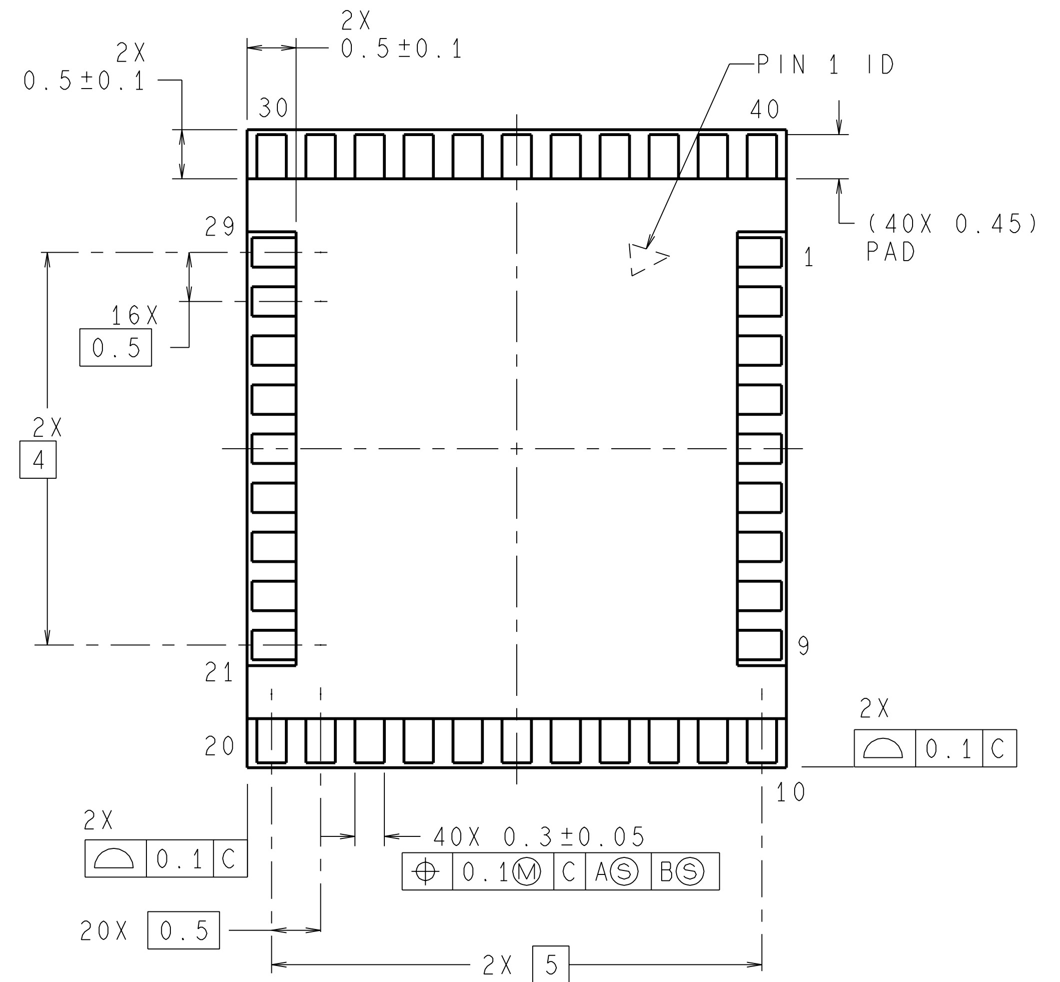
REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12453	05/11/2000	TL/WL



RECOMMENDED LAND PATTERN
1:1 RATIO WITH PACKAGE SOLDER PADS





DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. MATERIAL: BT RESIN CCL-HL832 WITH TAIYO PSR4000 AUS5 SOLDER MASK.
2. PLATING: Cu 15 TO 20 MICROMETERS (FULL)
   Ni 10 ± 5 MICROMETERS (LEADS ONLY)
   Au 1 ± 0.5 MICROMETER (LEADS ONLY)
3. REFERENCE JEDEC MO-208, VARIATION KFEA, DATED DECEMBER 1999.

APPROVALS	DATE
DRAWN T. LEQUANG	05/11/2000
DFTG. CHK. MARTA SUCHY	05/11/2000
ENGR. CHK. WAYNE LEE	05/11/2000

National Semiconductor
2900 Semiconductor Dr, Santa Clara, CA 95052-8090

CSP, PLASTIC, LAMINATED, 6.5 X 5.5 X 1.0 mm BODY, 40 L, 0.5 mm PITCH, GENERIC

PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV
INCH [MM]	N/A	C	(SC)MKT-SLB40B	A

DO NOT SCALE DRAWING | SHEET 1 of 1